

SPECIFICATION FOR APPROVAL

CUSTOMER: _____ PART NO: _____

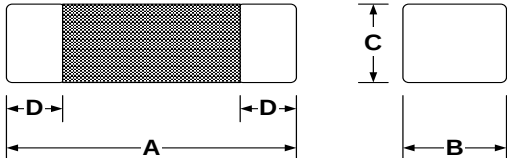
DESCRIPTION: FHB2012-150-NP SUBMIT NO: _____

QUANTITY: _____ PCS DATE: _____

CUSTOMER :		PART NO.	
SPECIFICATIONS		DATE	
PART NAME	DATA SHEET	SPEC(TYPE)	FHB2012-150-NP

TEST INSTRUMENT

- 1.HP4291A RF IMPEDANCE / MATERIAL ANALYZER FOR Z
- 2.DIGITAL MULTIMETER SC-7401 FOR RDC
- 3.Rated Current (mA)Max, : 300(Thermometer&HP6632A or HP6632A or HP42841A or CH301A)

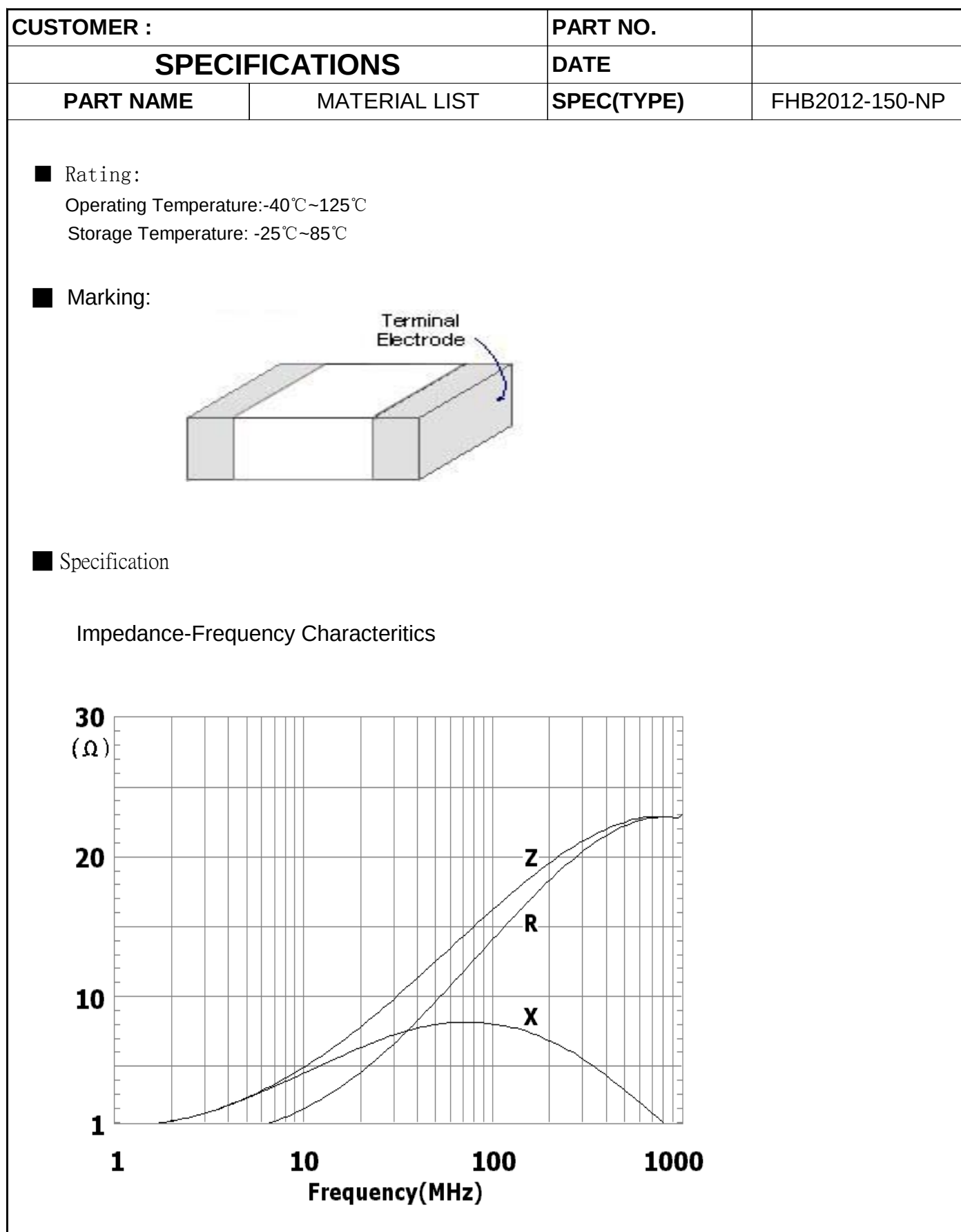


● PRODUT IDENTIFICATION:

FHB	20	12	-	150	-	NP
1	2	3		4		5

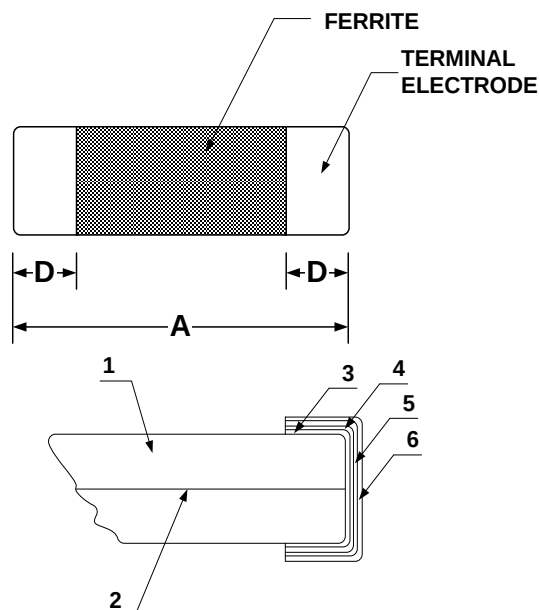
1.PRONDUCT SYMBOL 2.OUT SIDE DIA:mm
3.BODY HEIGHT :mm 4.Normal impedance
5.Meet ROHS Regulations of Prohibiped 6 Poisonous Materials

ELECTRICAL CHARACTERISTICS				DIMENSION				
ITEM	Z(Ω)	RDC(Ω)	IDC(mA)		A	B	C	D
SPEC.	100MHz	Max.	Max.		m/m	m/m	m/m	m/m
	15±25%	0.03	3000		2.0±0.2	1.25±0.2	0.9±0.2	0.5±0.30
1								
2								
3								
4								
5								
6								
7								
8								
9								
10								
X								
R								
TEST CONDITION		TEMP:	25℃		HUMIDITY:		50%	
DRAWN BY			CHECKED BY			APPROVED BY		
张达			黎敏			邓锋		



CUSTOMER :		PART NO.	
SPECIFICATIONS		DATE	
PART NAME	Series Specification	SPEC(TYPE)	FHB2012-150-NP

■ Construction:



NO	PART	MATERLAL
1	Ferrite Substance	NiO-CuO-ZnO-Ferrite
2	Silver electrode	Ag
3	Silver electrode	Ag
4	Cu plating	Cu
5	Ni plating	Ni
6	Sn plating	Sn

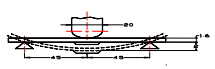
■ Standard Testing Condition

	Unless otherwise specified	In case of doubt
Temperature	Ordinary Temperature(15 to 35℃)	20±2℃
Humidity	Ordinary Humidity(25 to 85% RH)	60 to 70 % RH

CUSTOMER :		PART NO.	
SPECIFICATIONS		DATE	
PART NAME	MATERIAL LIST	SPEC(TYPE)	FHB2012-150-NP

■ Reliability of Chip Beads (FHB SERIES)

1.Mechanical Performance

NO	Item	Specification	Test Method
1	Flexure Strength	Appearance :No damage L change :within $\pm 10\%$ Q change :within $\pm 30\%$	Test device shall be soldered on the substrate Substrate Dimension:100*40*1.6mm Deflection:2.0mm Keeping Time:30sec For 100505,substratedimension is 100*40*0.8mm 
2	Vibration		Test device shall be soldered on the substrate Oscillation Frequency : 10 to 55to 10Hz for Amplitude : 1.5mm Time : 2hrs for each axis (X , Y & Z), TOTAL
3	Resistance to Soldering Heat	Appearance :No damage More than 75% of the terminal Electrode should be covered with solder. Impedance: with in $\pm 15\%$ of initial value. Q: within $\pm 30\%$ of initial value	Pre-heating: 150℃ , 1min Solder Composition: Sn/3.0Ag/0.5Cu Solder Temperature:260 $\pm 5^{\circ}\text{C}$ Immersion Time:10 $\pm 1\text{SEC}$ Measured after exposure in the room condition for 24hrs
4	Solderability	The electrodes shall be at least 90% covered with new solder coating	Pre-heating : 150℃ ,1min Solder Composition :Sn / Pn =63/37 Solder Temperature :230 $\pm 5^{\circ}\text{C}$ Immersion Time :4 $\pm 1\text{sec}$

CUSTOMER :		PART NO.	
SPECIFICATIONS		DATE	
PART NAME	MATERIAL LIST	SPEC(TYPE)	FHB2012-150-NP

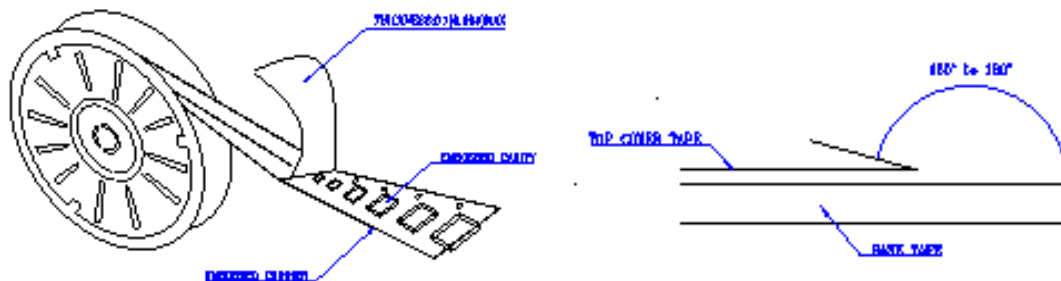
■ Reliability of Chip Beads (FHB SERIES)
Environmental Performance

NO	Item	Specification	Test Method		
1	Temperature Cycle	Appearance : No damage	Once cycle:		
		L change : within±10%	Step	Temperature (°C)	Time(min)
		Q change : within±30%	1	-25±3	30
			2	25±2	3
			3	85±3	30
			4	25±2	3
			Total:100chcles Measured after exposure in the room condition for 24hrs		
2	Humidity Resistance		Temperature :40±2℃ Relative Humidity : 90~95% Time : 1000hrs Measured after exposure in the room condition for 24hrs		
3	Heat Temperature Resistance		Temperature :85±3℃ Relative Humidity :20% Applied Current: Rated Current Time :1000hrs Measured after exposure in the room condition for 24hrs		
4	Low Temperature Resistance		Temperature :-25±3℃ Relative Humidity:0% Time : 1000hrs Measured after exposure in the room condition for 24hrs		

CUSTOMER :		PART NO.	
SPECIFICATIONS		DATE	
PART NAME	CARRIER & REEL	SPEC(TYPE)	FHB2012-150-NP

■ PACKAGING

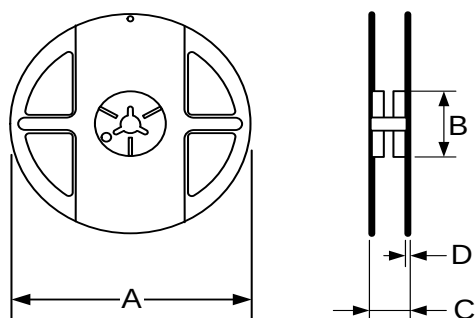
Packaging – Cover tape



Packaging Quantity

TYPE	BULK	PCS/REEL
FHB-2012	✓	4000

■ REEL DIMENSION :m/m



TYPE	A	B	C
FHB-2012	178	60	12